

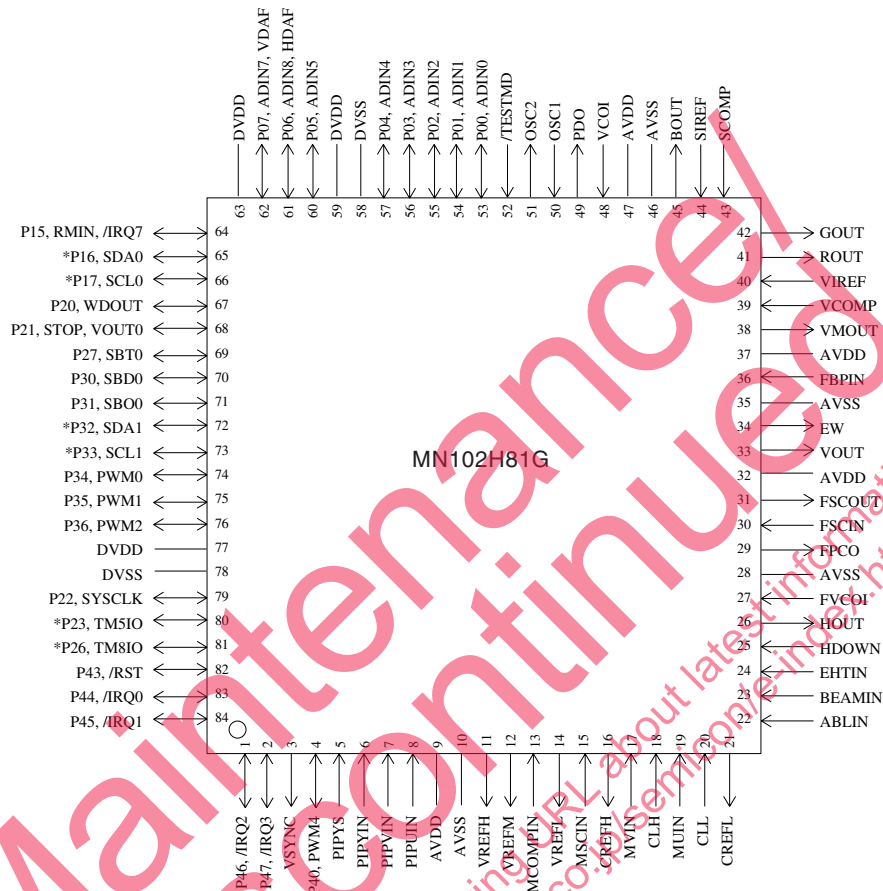
# □ MN102H81G

Type	MN102H81G		
ROM (×8-bit)	128 K		
RAM (×8-bit)	4 K		
Package	QFP084-P-1818E *Lead-free		
Minimum Instruction Execution Time	83 ns (at 3.135 V to 3.465 V, 12 MHz)		
Interrupts	External (5 lines) Internal (28 lines) : Timer × 11, A/D × 1, Undefined command × 1, RESET × 1, OSD × 2, Serial × 1, I <sup>2</sup> C × 1, Caption × 2, Remote control × 1, Address coincidence × 4, HSYNC × 1, VSYNC × 1		
Timer Counter	8-bit timer × 10 Watchdog timer: 17-bit × 1		
Serial Interface	I <sup>2</sup> C × 1: for multimaster mode, bus line (output) has 2 systems Sync serial / UART × 1		
Caption	• Built-in sync separator × 1		
I/O Pins	I/O	30	• Common use
A/D Inputs	10-bit × 8-ch. (with S/H)		
PWM	8-bit × 6-ch.		
Special Ports	Remote control reception		
CRTC	3-layer display (graphics, characters, splits)		
Notes	Remote control input discriminant circuit built-in, built-in NTSC video signal processing circuit, built-in 3-line comb filter		

Maintenance Discontinued

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Pin Assignment



QFP084-P-1818E \*Lead-free

\*5 V dielectric Nch open drain output pin

Support Tool

In-circuit Emulator

PX-ICE102H81-QFP084-P-1818E

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